

1.6x0.6mm RIGHT ANGLE SMD CHIP LED **LAMP**

Part Number: APA1606SECK

Super Bright Orange

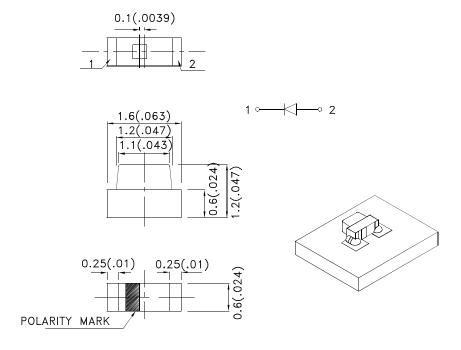
Features

- 1.6mmx0.6mm right angle SMT LED,1.2mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package :2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		21	Min.	Тур.	201/2
APA1606SECK	Super Bright Orange (AlGaInP)	WATER CLEAR	70	250	110°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	I==20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	I=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	I==20mA
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	I==20mA
lR	Reverse Current	Super Bright Orange		10	uA	V _R =5V

Notes:

- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

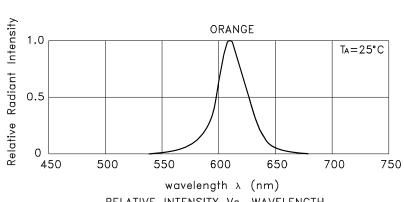
Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units			
Power dissipation	75	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	195	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

Note:

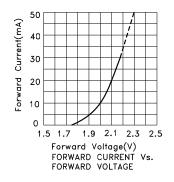
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

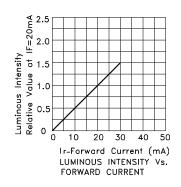
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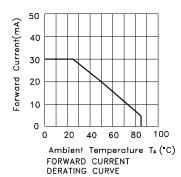


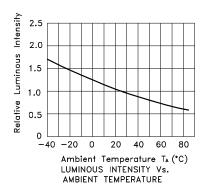
RELATIVE INTENSITY Vs. WAVELENGTH

Super Bright Orange APA1606SECK









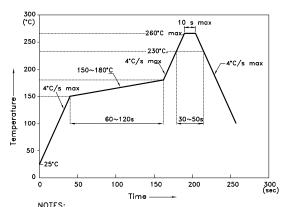
30 1.0 50° 60° 70° 80° 0.7 90° SPATIAL DISTRIBUTION

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APA1606SECK

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



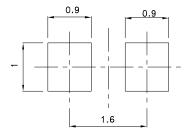
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

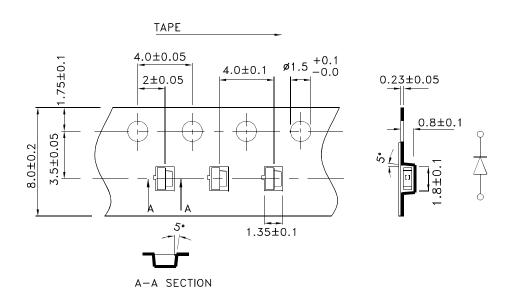
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. to high temperature.

 3.Number of reflow process shall be 2 times or less.

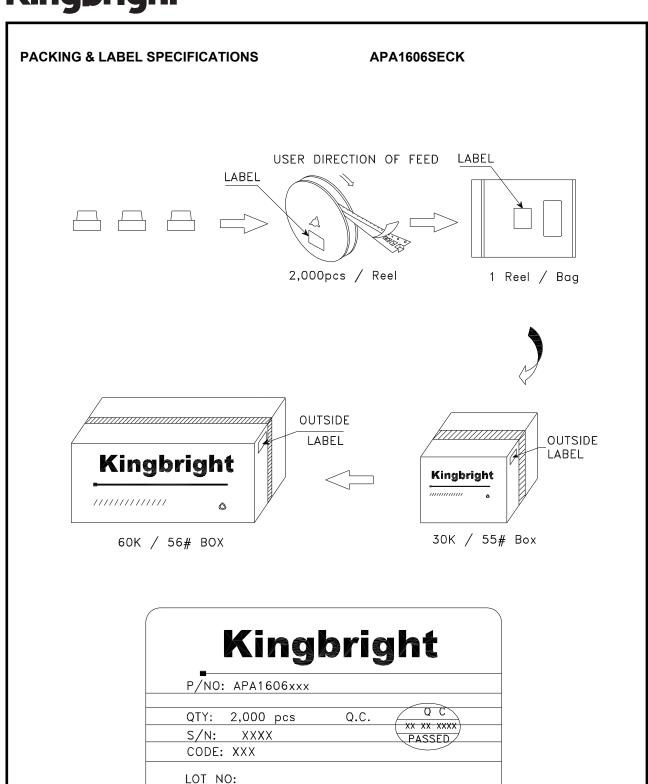
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)



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RoHS Compliant

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